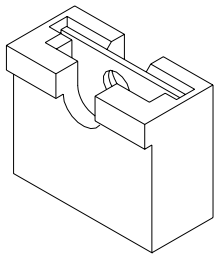
FEATURES AND SPECIFICATIONS

2.54mm (.100") Pitch C-Grid® Micro Shunt

90059

Low Profile



Features and Benefits

- Fully stackable
- Center probe hole—for continuity testing and easy pull-off
- Color-coded housings for plating and identification
- Delivered on break-off carrier strips for easy handling (10 per strip)
- Recommended to be applied after mating header is soldered

Reference Information

Product Specification: PS-90059
Packaging: Strips
UL File No.: E29179
CSA File No.: LR19980
Designed In: Inches

Electrical

Voltage: 350V
Current: 3.0A Gold; 1.5A Tin
Contact Resistance: 12mΩ max. Gold; 15mΩ max. Tin
Dielectric Withstanding Voltage: 2000V
Insulation Resistance: 2000 MΩ max.

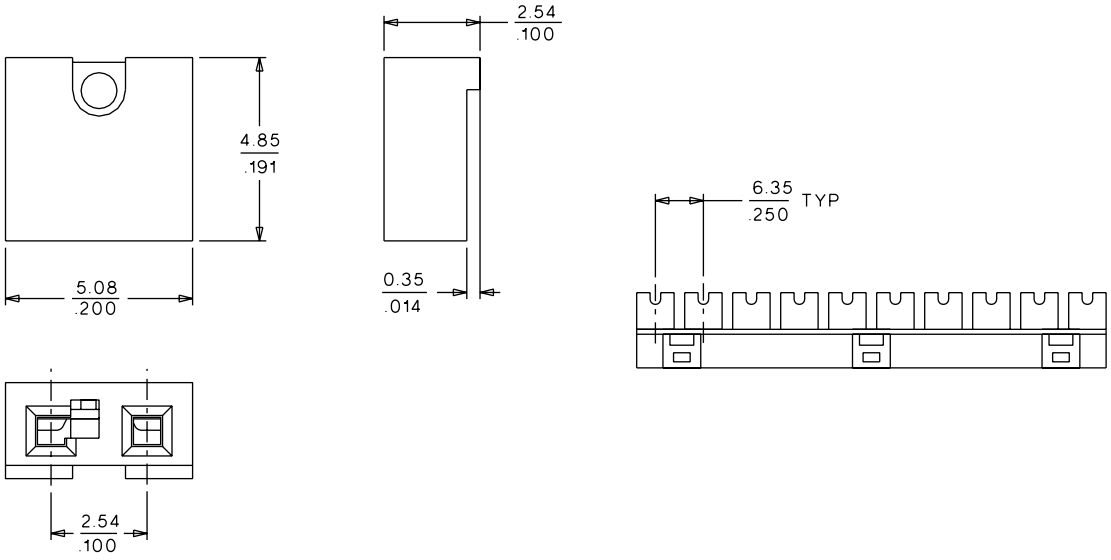
Mechanical

Mating Force: 7N max.
Unmating Force: 0.3N Gold; 0.5N Tin min.
Durability: 50 cycles Gold and 20 cycles Tin

Physical

Housing: Glass-filled polyester, UL 94V-0
Contact: Phosphor Bronze
Plating: See Table
Operating Temperature: -55 to +125˚C
Height: 4.95mm (.195") max.

CATALOG DRAWING (FOR REFERENCE ONLY)



ORDERING INFORMATION

Order No.	Plating No.	Color
• 90059-0009*	1	White
• 90059-0007*	2	Black
90059-0013	3	Black
90059-0014	4	White
90059-0012	5	White

• US Standard Product, available through Molex franchised distributors

* Preferred Version In Europe/Americas

Plating No. 1: 0.38μm (15μ") Gold in contact area over 0.76μm (30μ") Nickel with Gold flash overall

Plating No. 2: 5.0μm (200μ") min. Tin over 0.2μm (8μ") min. Copper

Plating No. 3: 0.9μm (35μ") min. Pretinned

Plating No. 4: 0.1μm (4μ") min. Gold over 1.0μm (40μ") min. Nickel overall

Plating No. 5: 0.76μm (30μ") Gold over 1.27*μm (50μ") Nickel in contact area with 0.2μm (8μ") min. Nickel overall